

## CBR08C849DAGAC

**General Information** 

Series

Style

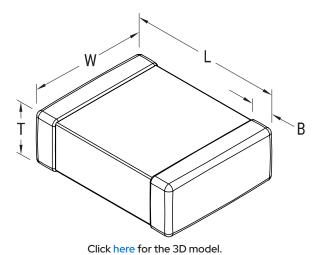
Description

CBR-SMD RF COG, Ceramic, 8.4 pF, +/-0.5 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805

CBR-SMD RF COG

SMD, Fixed, RF, Ultra High Q,

SMD Chip



Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No 12.03 mg Typical Component Weight Notes Solder Wave or Solder Reflow. Shelf Life 78 Weeks MSL 1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
т	0.85mm +/-0.1mm
В	0.5mm +/-0.2mm

Packaging Specifications

Packaging Packaging Quantity T&R, 180mm, Plastic Tape 4000

Specifications	
Capacitance	8.4 pF
Tolerance	+/-0.5 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.176%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	568

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